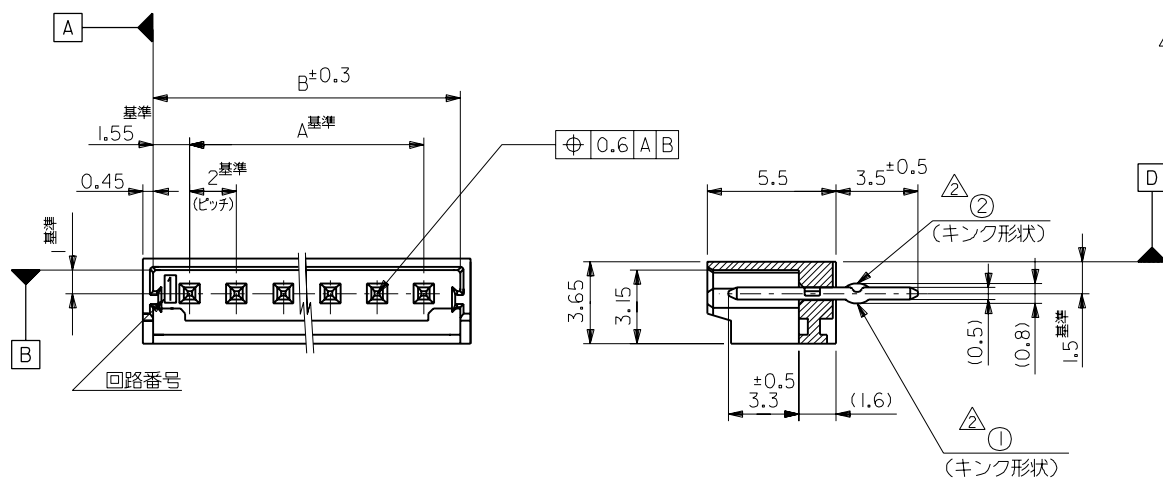
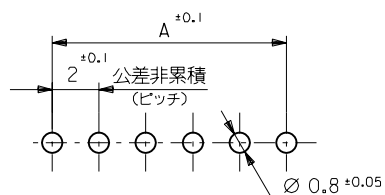




注 記

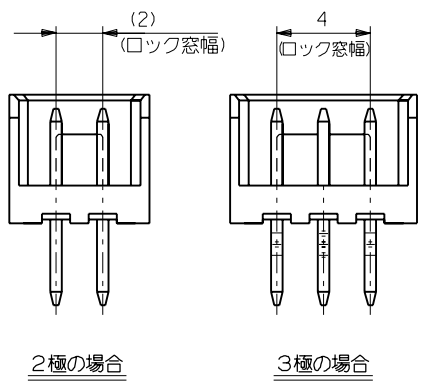
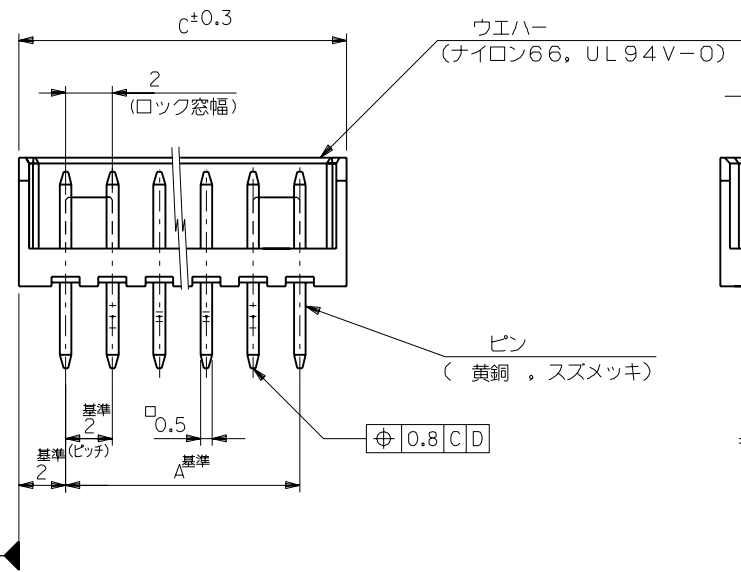
- 1 嵌合相手: 51065-**-00
 2 キンフは下記表の位置及び形状に付加のこと。 2極はキンフ無し。

回路番号	1	2	3	4	5	N-2	N-1	N
6 極以上	—	①	②	—	—	②	①	—
5 極	①	②	—	②	①	—	—	—
4 極	①	②	②	①	—	—	—	—
3 極	①	②	①	—	—	—	—	—



基板取付穴寸法 (参考)
 (t = 1.6)

32	31.1	28	53253-1510	15
30	29.1	26	-1410	14
28	27.1	24	-1310	13
26	25.1	22	-1210	12
24	23.1	20	-1110	11
22	21.1	18	-1010	10
20	19.1	16	-0910	9
18	17.1	14	-0810	8
16	15.1	12	-0710	7
14	13.1	10	-0610	6
12	11.1	8	-0510	5
10	9.1	6	-0410	4
8	7.1	4	-0310	3
6	5.1	2	53253-0210	2
C	B	A	ENG NO.	極数



2極の場合

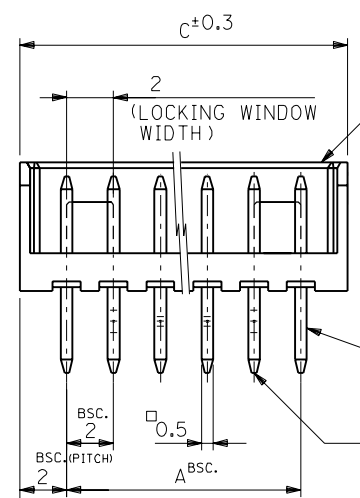
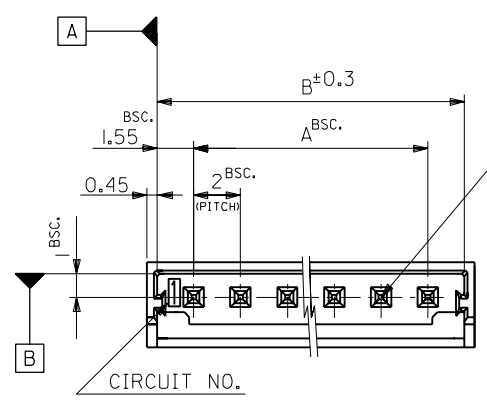
3極の場合

角度 ANGLE	±3°	変更 (J20439)	1.5	92/1/1	材料 MATERIAL	図中参照	moLEX MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
30 以上 OVER	±0.3	B 変更 (J10095)	1.5	91/2/8	仕上げ FINISH	図中参照	EDP. NO.
10 以上 30 未満 UNDER	±0.25	A 変更 (J00016)	1.5	90/1/11	適用電線範囲 WIRE RANGE	—	ENG. NO.
10 未満 UNDER	±0.2	O 新規作成 (J91084)	1.5	89/2/20	被覆外径 INS. RANGE	—	SD-53253-**-10
一般公差 GENERAL TOLERANCES		記号 LTR 変更内容 REVISION RECORD	DR. CHK. DATE	日付 DATE	DRAWN BY 89/9/21 S. AIHARA	CHK'D BY 91/3/91 M. KUKUSHIMA	TITLE 名称 NEW 2.0 WIRE TO BOARD CONN. WAFER ASS'Y (ST.)
		REVISION RECORD	DR. CHK. DATE	日付 DATE	APP'D BY 91/3/91 M. KUKUSHIMA	SCALE 5-1	REV C

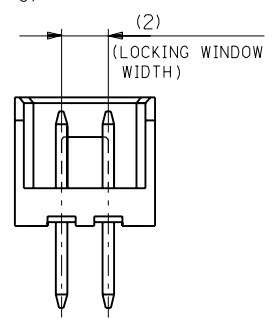
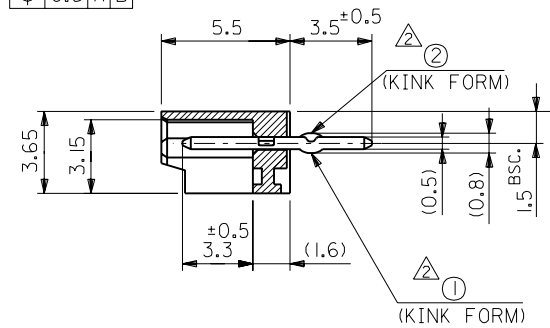
ENG. NO.
SD-53253-**-10

EDP NO.

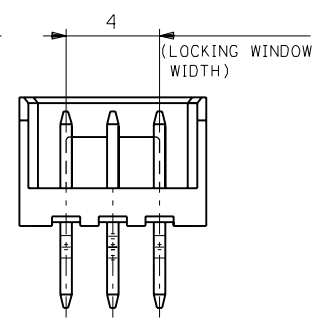
MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING



0.6 A B



IN CASE OF
2 CIRCUIT WAFER

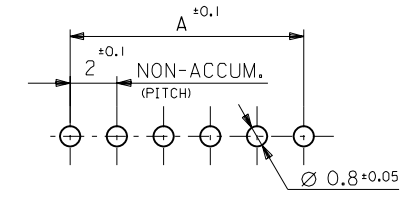


IN CASE OF
3 CIRCUIT WAFER

NOTES

1. MATES WITH: 51065-**-00
2. KINK TO BE APPLIED AS FOLLOWS, 2 CIRCUIT HAS NO KINK

CKT NO.	1	2	3	4	5	N-2	N-1	N
6 CKT	—	①	②	—	—	②	①	—
5 CKT	①	②	—	②	①	—	—	—
4 CKT	①	②	②	①	—	—	—	—
3 CKT	①	②	①	—	—	—	—	—



RECOMMENDED P.C. BOARD HOLE
DIMENSION (REFERENCE)
(t = 1.6)

32	31.1	28	53253-1510	15
30	29.1	26	-1410	14
28	27.1	24	-1310	13
26	25.1	22	-1210	12
24	23.1	20	-1110	11
22	21.1	18	-1010	10
20	19.1	16	-0910	9
18	17.1	14	-0810	8
16	15.1	12	-0710	7
14	13.1	10	-0610	6
12	11.1	8	-0510	5
10	9.1	6	-0410	4
8	7.1	4	-0310	3
6	5.1	2	53253-0210	2
C	B	A	ENG NO.	CKT

角度	ANGLE	°
30以上	OVER	+3°
10以上 30未満	OVER	+0.3
10未満	UNDER	+0.25
10未満	UNDER	+0.2
一般公差	GENERAL TOLERANCES	

	C	REVISED (J20439)	1.1 MS 9/2/17
	B	REVISED (J10095)	1.1 S1 9/12/8
3	A	REVISED (J00016)	90/11/11
25	O	PROPOSED (J91084)	89/12/20
記号	変更内容		DR.
17F	REVISION RECORD	CHK.	DATE
REVISE ONLY ON CAD SYSTEM			

材料	REFER TO DRAWING
仕上げ	REFER TO DRAWING
適用電線範囲	WIRE RANGE
被覆外径	INS. RANGE
DRAWN BY	CHK'D BY
APP'D BY	SCALE

材料	MOLEX-JAPAN CO.,LTD.
EDP NO.	SD-53253-**-10
ENG. NO.	REV C
TITLE 名称	NEW 2.0 WIRE TO BOARD CONN. WAFER ASS'Y (ST.)

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